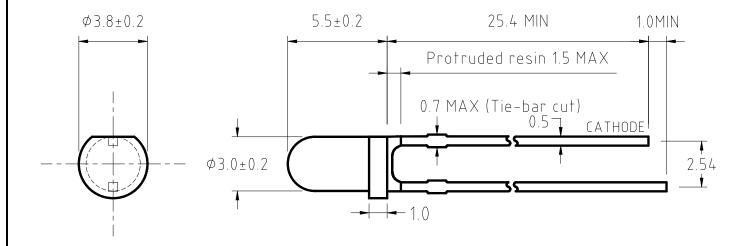


3mm White LED Lamp

PACKAGE OUTLINES



Item	Material
Resin	Epoxy Resin
Lead Frame	Ag Plating on SPCC

Note: All dimensions are in millimeters tolerance is ±0.1mm unless otherwise noted.

Part Number	Material	Lens	Color
Fait Number	iviatei iai	Emitted	Lens
L314NWC-30D	InGaN	White	Water Clear



3mm White LED Lamp

ABSOLUTE MAXIMUM RATINGS

(Ta=25°C)

Parameter	Symbol	Ratings	Unit	
Forward Current	lf	30	mA	
Peak Forward Current (Duty 1/10@10ms)	Ifp	100	mA	
Power Dissipation	Pd	108	mW	
Reverse Voltage	Vr	5	V	
Operating Temperature Range	Topr	-25~+85	°C	
Storage Temperature Range	Tstg	-35~+100	°C	
Solder Dipping Temperature	Tsld	260°C for 5 sec		

OPTICAL-ELECTRICAL CHARACTERISTICS

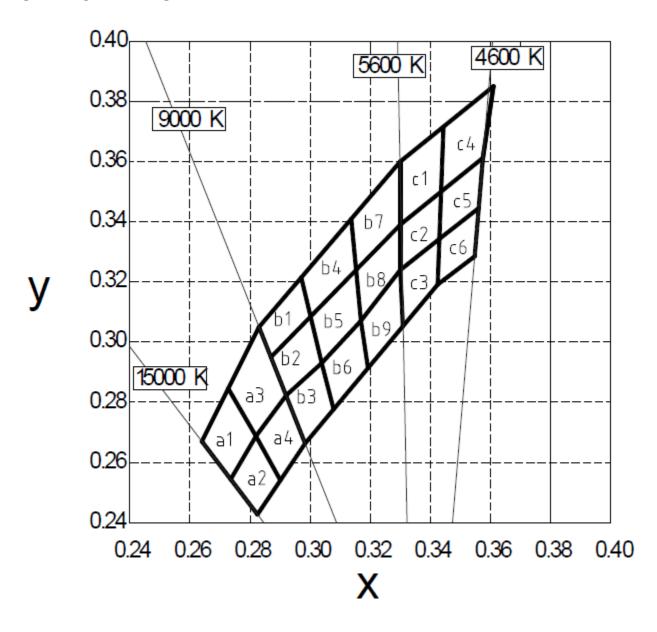
(Ta=25°C)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv		7000	10000		mcd
Chromaticity Coordinate	X Y			0.31 0.32		
Forward Voltage	Vf	I _F =20mA		3.2	3.6	V
Viewing Angle	201/2			30		deg
Reverse Current	lr	Vr=5V			50	μA



3mm White LED Lamp

CHROMATICITY DIAGRAM





3mm White LED Lamp

COLOR RANKS

	Ran	ıka	Color T	empera	ture	9000	K — 150	000 K	
		al					a2		
X	0.2736	0.2640	0.2728	0.2820	X	0.2825	0.2736	0.2820	0.2900
y	0.2544	0.2670	0.2846	0.2687	y	0.2427	0.2544	0.2687	0.2539
		a3			a4				
X	0.2820	0.2728	0.2830	0.2920	X	0.2910	0.2820	0.2920	0.2984
y	0.2687	0.2846	0.3050	0.2823	y	0.2541	0.2687	0.2823	0.2663
			•				•		

	Ra	nk b	Color 7	Tempera	ature	5600	K — 90	00 K	
		b1					b2		
X	0.2870	0.2830	0.2971	0.3002	X	0.2920	0.2870	0.3002	0.3039
y	0.2950	0.3050	0.3215	0.3085	y	0.2823	0.2950	0.3085	0.2930
		b3					b4		
X	0.2984	0.2920	0.3039	0.3078	X	0.3002	0.2971	0.3137	0.3153
y	0.2663	0.2823	0.2930	0.2777	y	0.3085	0.3215	0.3409	0.3240
		b5			b6				
X	0.3039	0.3002	0.3153	0.3169	X	0.3078	0.3039	0.3169	0.3193
y	0.2930	0.3085	0.3240	0.3071	y	0.2777	0.2930	0.3071	0.2914
		b 7					b8		
X	0.3153	0.3137	0.3300	0.3300	X	0.3169	0.3153	0.3300	0.3300
y	0.3240	0.3409	0.3600	0.3390	y	0.3071	0.3240	0.3390	0.3239
		Ь9							
x	0.3193	3.3169	0.3300	0.3309					
y	0.2914	0.3071	0.3239	0.3053					



3mm White LED Lamp

	Ra	nk c	Color T	Tempera	ature	4600	K – 56	00 K	
	c1						c2		
X	0.3300	0.3300	0.3444	0.3436	X	0.3300	0.3300	0.3436	0.3430
y	0.3390	0.3600	0.3716	0.3500	y	0.3239	0.3390	0.3500	0.3343
		c3			c4				
X	0.3309	0.3300	0.3430	0.3425	X	0.3436	0.3444	0.3610	0.3575
y	0.3053	0.3239	0.3343	0.3192	y	0.3500	0.3716	0.3850	0.3612
		c5					с6		
X	0.3430	0.3436	0.3575	0.3561	X	0.3425	0.3430	0.3561	0.3548
y	0.3343	0.3500	0.3612	0.3445	Y	0.3192	0.3343	0.3445	0.3285

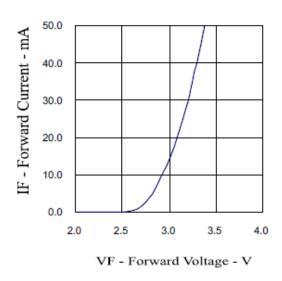
Note: one delivery will include several color ranks and Iv ranks of products. The quantity-ratio of different rank is decided by American Opto Plus LED Corp.



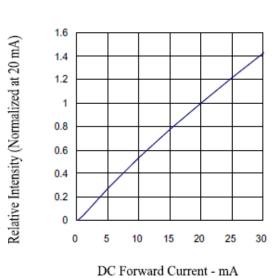
3mm White LED Lamp

TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVES

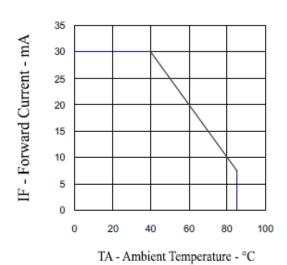
Forward Current vs. Forward Voltage



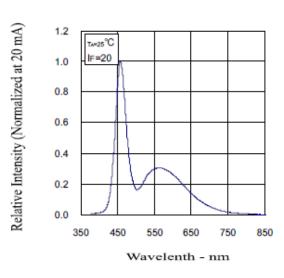
Relative Intensity vs. Forward Current



Forward Current vs. Ambient Temperature



Relative Intensity vs. Wavelength





3mm White LED Lamp

SOLDERING CONDITIONS

- Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- Recommended soldering conditions

	Dip Soldering						
Pre-Heat		100°C Max.					
Pre-Heat Time		60 sec. Max.					
Solder Bath Temp	erature	260°C Max.					
Dipping Time		5 sec. Max.					
Dipping Position		No lower than 3mm fro	om the base of the epoxy bulb.				
		Hand Solderin	ng				
0000		_	Others (Including Lead-Free				
	3Ø Serie	2 8	Solder)				
Temperature	300°C M	ax.	350°C Max.				
Soldering time	3 sec. Max.		3 sec. Max.				
Position	No closer than 3mm from		No closer than 3mm from				
	the base of the epoxy bulb.		the base of the epoxy bulb.				

- Do not apply any stress to the lead, particularly when heated
- The LEDs must not be repositioned after soldering
- After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be
 caused by the PC board warping or from the clinching and cutting of the leadframes. When it
 is absolutely necessary, the LEDs may be mounted in this fashion, but, the User will assume
 responsibility for any problems. Direct soldering should only be done after testing has
 confirmed that no damage, such as wire bond failure or resin deterioration, will occur.
 Sander's LEDs should not be soldered directly to double sided PC boards because the heat
 will deteriorate the epoxy resin.
- When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- Cut the LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause LED failure.